

I claim:

1. A lead frame package with dummy chip comprising:

a lead frame with a plurality of first leads;

a molding compound;

a dummy chip and a die, wherein said molding compound encapsulates said die and said dummy chip, said dummy chip being arranged on a lower portion of said molding compound, said die being stacked on an upper surface of said dummy chip by using an adhesive material; and

tapes connected between said die and an end of said plurality of first leads over said dummy chip.

2. The package of claim 1, wherein said dummy chip is formed of silicon.

3. The package of claim 1, wherein said dummy chip refers to a substrate without IC formed therein.

4. The package of claim 1, wherein said dummy chip is exposed by said molding compound, which can improve the efficiency of spreading heat.

5. The package of claim 1, further comprises a tape to fix said plurality of first leads.

6. The package of claim 1, wherein said lead frame further comprises a plurality of second leads outside said dummy chip.

7. The package of claim 1, wherein said die is attached on said dummy chip by adhesive material.